

DATA SHEET

MOS FIELD EFFECT POWER TRANSISTORS

μ**ΡΑ1700Α**

SWITCHING N-CHANNEL POWER MOS FET INDUSTRIAL USE

DESCRIPTION

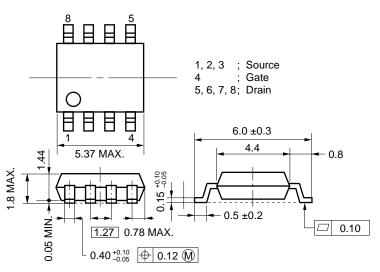
This product is N-Channel MOS Field Effect Transistor designed for DC/DC converters and power management of notebook computers.

FEATURES

- Low On-Resistance $R_{DS(on)1} = 27 \text{ m}\Omega \text{ Max.}$ (V_{GS} = 10 V, I_D = 3.5 A) $R_{DS(on)2} = 50 \text{ m}\Omega \text{ Max.}$ (V_{GS} = 4 V, I_D = 3.5 A)
- Low Input Capacitance Ciss = 820 pF Typ.
- Built-in G-S Protection Diode
- Small and Surface Mount Package (Power SOP8)

PACKAGE DIMENSIONS

(in millimeter)



ABSOLUTE MAXIMUM RATINGS (T_A = 25 °C, all terminals are connected)

Drain to Source Voltage	VDSS	30	V	Drain
Gate to Source Voltage	Vgss	±20	V	↓
Drain Current (DC)	D(DC)	±7.0	А	Body
Drain Current (pulse) ^{Note 1}	D(pulse)	±28	А	
Total Power Dissipation $(T_A = 25 \ ^{\circ}C)^{Note 2}$	Рт	2.0	W	Gate
Channel Temperature	Tch	150	°C	Protection
Storage Temperature	Tstg	–55 to +150	°C	Diode Source

Notes 1. PW \leq 10 μ s, Duty Cycle \leq 1 %

2. Mounted on ceramic substrate of 1200 $\text{mm}^2\times 1.7~\text{mm}$

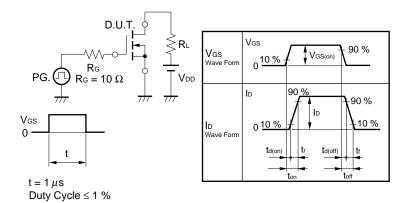
The diode connected between the gate and source of the transistor serves as a protector against ESD. When this device acutally used, an additional protection circuit is externally required if voltage exceeding the rated voltage may be applied to this device.

The information in this document is subject to change without notice.

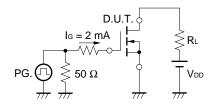
CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Drain to Source On-state Resistance	RDS(on)1	Vgs = 10 V, Id = 3.5 A		18	27	mΩ
	RDS(on)2	Vgs = 4 V, Id = 3.5 A		28	50	mΩ
Gate to Source Cutoff Voltage	VGS(off)	V _{DS} = 10 V, I _D = 1 mA	1.0	1.6	2.0	V
Forward Transfer Admittance	y _{fs}	VDS = 10 V, ID = 3.5 A	5.0	9.0		S
Drain Leakage Current	Idss	Vds = 30 V, Vgs = 0			10	μA
Gate to Source Leakage Current	lgss	$V_{GS} = \pm 20 \text{ V}, \text{ V}_{DS} = 0$			±10	μA
Input Capacitance	Ciss	Vds = 10 V		820		pF
Output Capacitance	Coss	V _{GS} = 0		350		pF
Reverse Transfer Capacitance	Crss	f = 1 MHz		160		pF
Turn-On Delay Time	t _{d(on)}	$I_{D} = 3.5 \text{ A}$ $V_{GS(on)} = 10 \text{ V}$ $V_{DD} = 15 \text{ V}$ $R_{G} = 10 \Omega$		18		ns
Rise Time	tr			98		ns
Turn-Off Delay Time	td(off)			57		ns
Fall Time	tr			32		ns
Total Gate Charge	QG	ID = 7.0 A		20		nC
Gate to Source Charge	QGS	VDD = 24 V		2.4		nC
Gate to Drain Charge	Qgd	V _{GS} = 10 V		5.6		nC
Body Diode Forward Voltage	VF(S-D)	IF = 7.0 A, VGS = 0		0.79		V
Reverse Recovery Time	trr	IF = 7.0 A, VGS = 0		36		ns
Reverse Recovery Charge	Qrr	di/dt = 100 A/µs		35		nC

ELECTRICAL CHARACTERISTICS (TA = 25 °C, all terminals are connected)

Test Circuit 1 Switching Time



Test Circuit 2 Gate Charge



1

0.1 0.1

TA = 25 °C Single Pulse

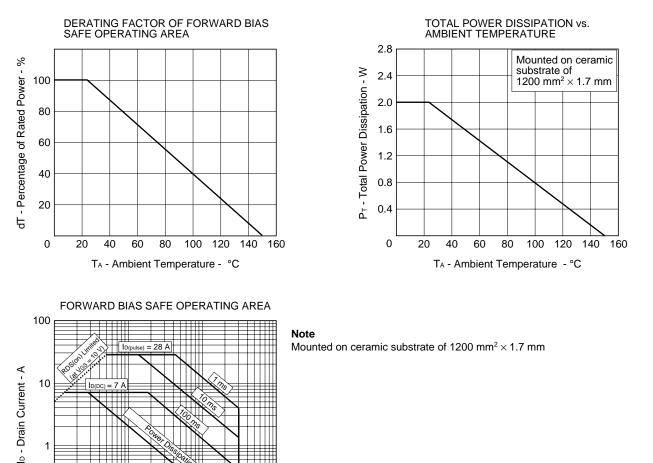
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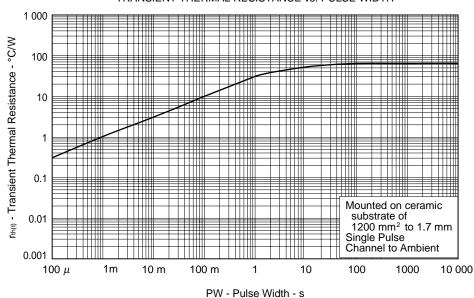
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VDS - Drain to Source Voltage - V

10

100





TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH

FORWARD TRANSFER CHARACTERISTICS 100 Pulsed Ip - Drain Current - A 10 125 °C Tch = 75 °C 1 25 °C 25 °C 0.1 # $V_{DS} = 10 V$ 2 4 0 6 8

Vgs - Gate to Source Voltage - V

FORWARD TRANSFER ADMITTANCE vs.

#

10

Vps = 10 V

Pulsed

DRAIN CURRENT

1

T_{ch} = -25 °C 25 °C 75 °C 125 °C

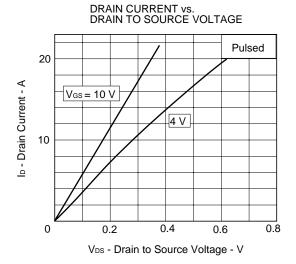
100

10

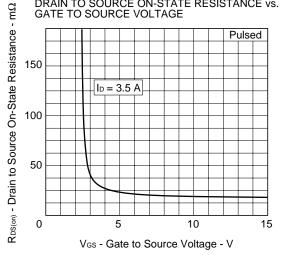
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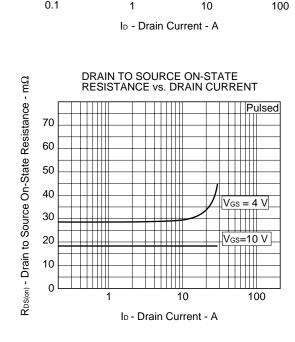
0.1

| y_{fs} | - Forward Transfer Admittance - S

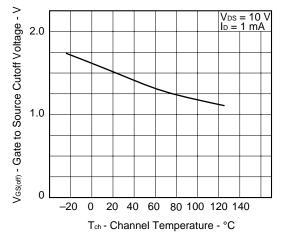


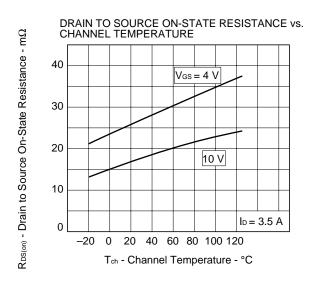
DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE

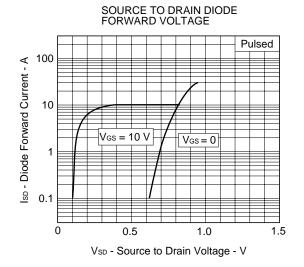




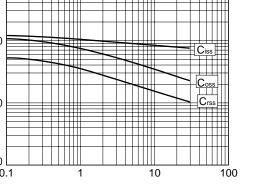
GATE TO SOURCE CUTOFF VOLTAGE vs. CHANNEL TEMPERATURE



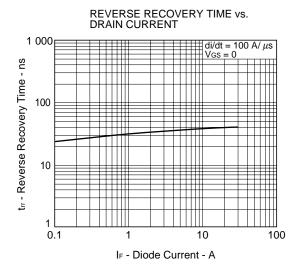




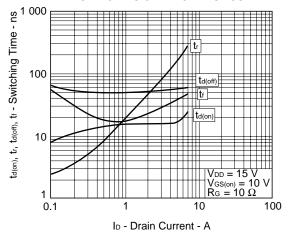
CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE 10 000 V_{GS} = 0 f = 1 MHz Ciss, Coss, Crss - Capacitance - pF 1 000 Ciss Ħ HT Coss Crss 100 10 0.1 10 100 1



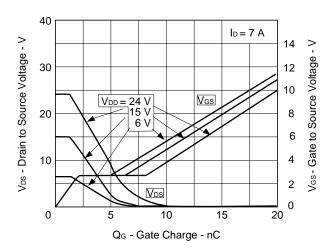
VDS - Drain to Source Voltage - V



SWITCHING CHARACTERISTICS



DYNAMIC INPUT/OUTPUT CHARACTERISTICS



REFERENCE

Document Name	Document No.	
NEC semiconductor device reliability/quality control system	C11745E	
Quality grade on NEC semiconductor devices	C11531E	
Semiconductor device mounting technology manual	C10535E	
Semiconductor device package manual	C10943X	
Guide to quality assurance for semiconductor devices	MEI-1202	
Application circuits using Power MOS FET	TEA-1035	
Safe operating area of Power MOS FET	TEA-1037	

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Anti-radioactive design is not implemented in this product.